Abstracts

Three-Dimensional MMIC Technology: A Possible Solution to Masterslice MMIC's on GaAs and Si

T. Tokumitsu, M. Aikawa and K. Kohiyama. "Three-Dimensional MMIC Technology: A Possible Solution to Masterslice MMIC's on GaAs and Si." 1995 Microwave and Guided Wave Letters 5.11 (Nov. 1995 [MGWL]): 411-413.

A novel masterslice MMIC is presented that expands the possibilities for three-dimensional (or multilayer) MMIC technology, This MMIC incorporates two levels of ground metals, resulting in an effective selection of master-array elements on the wafer surface by using the lower-level metal and a circuit-stacking effect by the upper one X-band amplifier and receiver MMIC's on 3 x 1 and 6 x 3 array-units, respectively, are also demonstrated in very small areas.

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